	COUNT	DESCRIPTION O		BY	Снкр	DATE	I	COUNT	DESCRIPTION OF RE		BY	CHKD	Δ	TE
Δ	00011	DESCREPTION		ы		DATE	Δ	000111	DESCREPTION OF RE	TION OF REVISIONS BY C			07	
$\overline{\Delta}$							$\overline{\Delta}$							
APF	LICA	BLE STANDAR	D											
Applicable Cable			-55°C	to +10	05°C (No	te1)	-	torage emperature Range -10°C to +60°C (N					3)	
			dity	20	% to 80	% (Note2	2)		Storage Humidity Range	% to	to 70% (Note3)			
		Applicable Conr	nector	DF51	K-*(D)S-2C (#	##)	Ň	/oltage	250V AC/DC				
		Applicable Cable	•	φ0.8 mm					Current	AWG 30 : 0.5A				
		Insulation Diame	eter											
						PECI	FIC	ATIO	-					
		ITEM		TE	ST ME	THOD			REQUIF	REMENT	S		QT	AT
CO	NSTR													
General Examination			Visually and by measuring instrument.						According to drawing.				0	0
Marking			Confirmed visually.											0
ELE	CTR	CAL CHARAC	TERISTIC	S										
Contact Resistance			20mV MAX, 1	mA (D	C or 10	00Hz).			30 mΩ MAX.				0	
Millivolt Level Method														-
		IICAL CHARA	I CTERISTIC	s										
Mechanical Operation (Sn Plating)									①Contact resistance: 3	$$ Contact resistance: 30m Ω MAX				
									②No damage, crack or looseness of parts.					-
Mechanical Operation			50 times insertion and extraction.						(Î)Contact resistance: $30m\Omega$ MAX					
(Au Plating)									②No damage, crack or looseness of parts.					-
Vibration			Frequency 10) to 55	Hz, sing	gle amplitu	ude 0	.75 mm,	①No electrical discontinuity of 1 μ s.				ο	
			at 10 cycles	for 3 d	irection.				②No damage, crack or looseness of parts.					
Shock		Acceleration	490 m	∕s² dura	tion of pu	ılse 1	1 ms at	3				0		
		times for 3 di	rectior	IS.										
					<u>د</u>									
	o Heat		CHARACTERISTICS Exposed at 40 ± 2 °C , humidity 90 to 95 %, 96 h.					①Contact resistance: 3		x				
		(Charde Chate)	(After leaving the room temperature for 1 to 2h.)						2No damage, crack or looseness of parts.				0	
		(Steady State,	After leaving	; the ro	om tem	perature	TOP 1	to Zn.)	(2)No damage, crack or	looseness	or par	ts.	U	
Rapid	Change	of	Temperature	−55 °(C→ +10	5 °C			①Contact resistance: 3	30 mΩ MA	X.			
Temperatur		e	Time 30min→ 30min Under 5 Cycles.						②No damage, crack or looseness of parts.					
			(The transfer	ring tin	ne of th	e tank is i	2 to 3	3 MIN)					0	
			(After leaving	the ro	om tem	perature	for 1	to 2h.)						
Rema	arks								1					

Rema

Note 1: Include the temperature rising by current.

Note 2: No condensing

Note 3: Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation.

			DRAV	٧N	DESIGN	ED	CHECKED	APPROVED	RELEASED	
			J.S C	ноі	J.S CHOI		S.M.LIM	T.S KANG		
			17.12	.22	17.12.22		17.12.22	17.12.22	DEPT	
Unless otherwise specified, refer to IEC 60512.									\smile	
NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST O: APPLICABLE TEST										
						PART NO.				
HIROSE KOREA CO.,LTE	SPECIFICATION SHE			1661	DF51K-30SCF (800)					
CODE NO.(OLD) DRAW		VING NO.		CODE	CODE NO.					
CL		ELC4-611494				CL 6652-0041-6-800				